Abstracts

Parasitic Impedance Analysis of Double Bonding Wires for High-Frequency Integrated Circuit Packaging

S.-K. Yun and H.-Y. Lee. "Parasitic Impedance Analysis of Double Bonding Wires for High-Frequency Integrated Circuit Packaging." 1995 Microwave and Guided Wave Letters 5.9 (Sep. 1995 [MGWL]): 296-298.

Double bonding wires separated by an internal angle have been characterized in a wide range of frequencies using the Method of Moments with the incorporation of the ohmic resistance. For a 30° internal angle, the calculated total reactance is more than 35% less than that of a single bonding wire due to the negative mutual coupling effect of different current directions. The radiation effect at high frequencies has been observed decreasing the mutual inductance between the angled bonding wires, whereas for parallel bonding wires it greatly increases the mutual inductance.

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